

PRODUCT SPECIFICATION **FOR LCD MODULE**

Revision: 1.0

Model No: LS022T03-MR-V1

Module Type: COG+FPC+B/L

APPROVED SIGNATURE

- ☒ Approved Product Specification only
- ☐ Approved Product Specification and Samples

For Customer's Acceptance

Approved by	Comment

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1. General Description

LS022T03-MR-V1 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 2.2 inch and the resolution is 240(RGB)*320, the panel can display up to 262k colors.

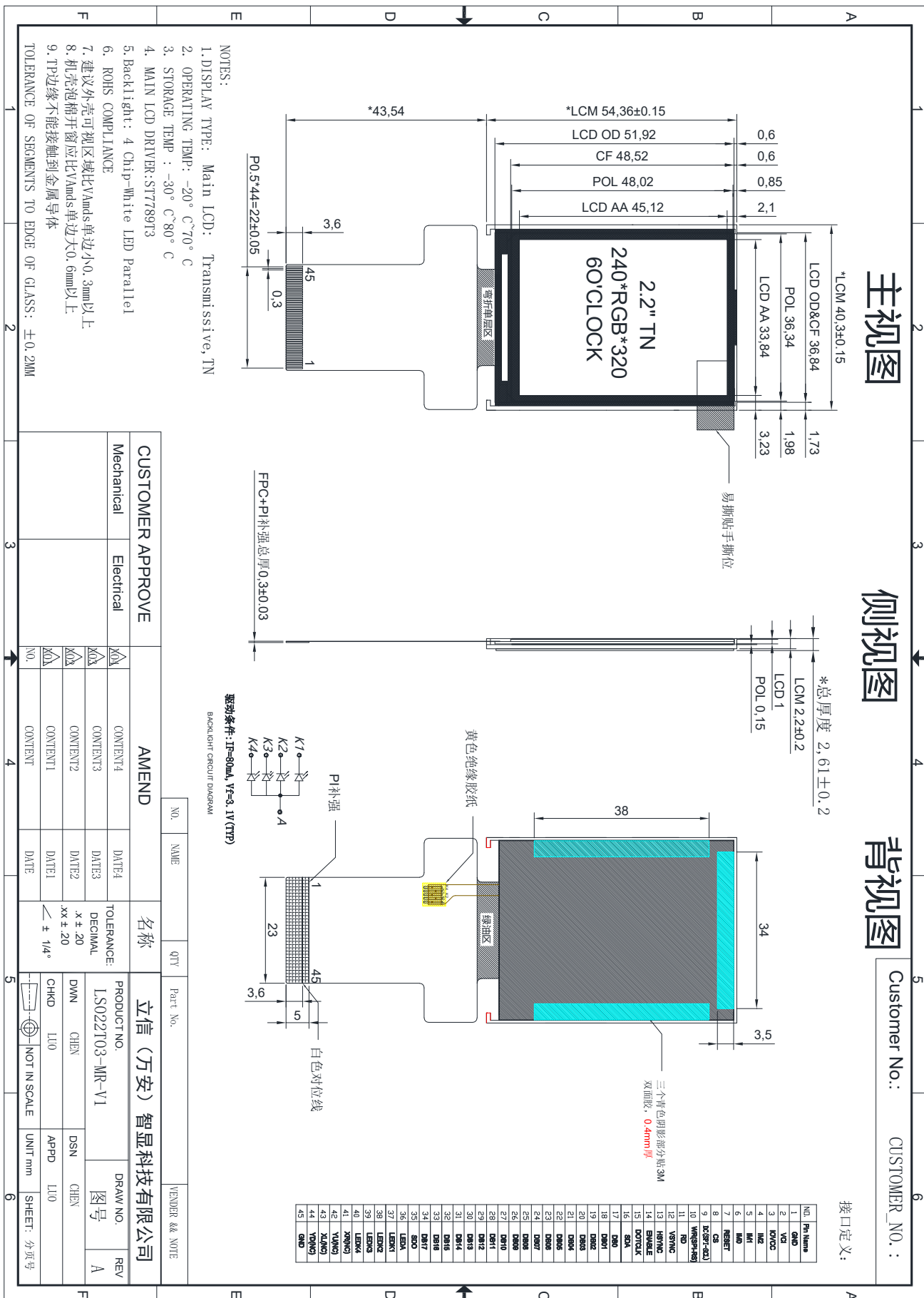
2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 240(RGB)×320 Dot-matrix
Input Data	8080/RGB/SPI
Viewing Direction (Grayscale Inversion)	TN
Drive	ST77789T3

3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	40.3 ×54.36 ×2.61	mm
Number of dots	240(RGB) ×320	pixel
Active area (H×V)	33.84×45.12	mm

4. Outline Dimension



5. Absolute Maximum Ratings

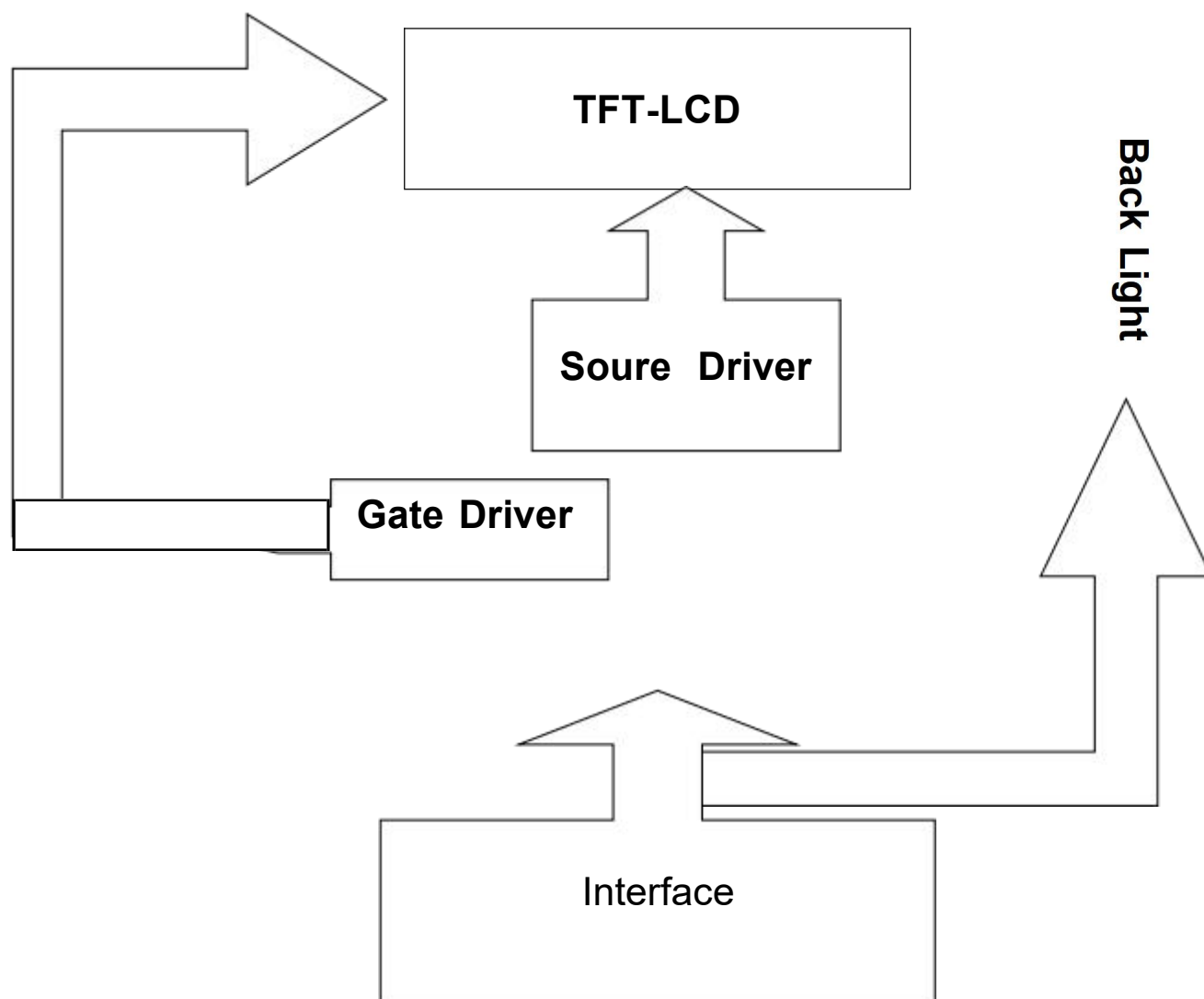
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VCC	-0.3	4.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	4.6	V	
Operating temperature	TOPR	-20	70	°C	
Storage temperature	TSTR	-30	80	°C	

6. Electrical Characteristics

Item		Symbol	Rating			Unit	Remark
			Min	Typ	Max		
Supply voltage		VCC	2.4	2.8	3.3	V	Note1
Supply voltage		IOVCC	1.65	1.8	3.3	V	
Input Voltage	L level	VIL	0	---	0.3*IOVCC	V	
	H level	VIH	0.7*IOVCC	---	IOVCC	V	

7. Module Function Description

7-1. Block Diagram Of LCM



7-2. Pin Description

PIN NO.	Symbol	I/O	Description																																										
1	GND	P	Ground																																										
2	VCI	P	Power supply																																										
3	IOVCC	P	Power supply																																										
4	IM2	I	<table><tr><th>IM3</th><th>IM2</th><th>IM1</th><th>IM0</th><th>MPU Interface Mode</th><th>Data pin</th></tr><tr><td>1</td><td>0</td><td>0</td><td>0</td><td>80-16bit parallel I/F II</td><td>DB[17:10], DB[8:1]</td></tr><tr><td>1</td><td>0</td><td>0</td><td>1</td><td>80-8bit parallel I/F II</td><td>DB[17:10]</td></tr><tr><td>1</td><td>0</td><td>1</td><td>0</td><td>80-18bit parallel I/F II</td><td>DB[17:0],</td></tr><tr><td>1</td><td>0</td><td>1</td><td>1</td><td>80-9bit parallel I/F II</td><td>DB[17:9]</td></tr><tr><td>1</td><td>1</td><td>0</td><td>1</td><td>3-line 9bit serial I/F II</td><td>SDA: in/ SDO: out</td></tr><tr><td>1</td><td>1</td><td>1</td><td>0</td><td>4-line 8bit serial I/F II</td><td>SDA:in/ SDO: out</td></tr></table>	IM3	IM2	IM1	IM0	MPU Interface Mode	Data pin	1	0	0	0	80-16bit parallel I/F II	DB[17:10], DB[8:1]	1	0	0	1	80-8bit parallel I/F II	DB[17:10]	1	0	1	0	80-18bit parallel I/F II	DB[17:0],	1	0	1	1	80-9bit parallel I/F II	DB[17:9]	1	1	0	1	3-line 9bit serial I/F II	SDA: in/ SDO: out	1	1	1	0	4-line 8bit serial I/F II	SDA:in/ SDO: out
IM3	IM2	IM1		IM0	MPU Interface Mode	Data pin																																							
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5	IM1	I																																											
6	IM0	I																																											
7	RESET	I	LCM Reset pin Signal is active low.																																										
8	CS	I	Chip selection pin																																										
9	DC(SPI_SCL)	I	Display data/command selection pin in parallel interface. -This pin is used to be serial interface clock. DCX='1': display data or parameter. DCX='0': command data. -If not used, please fix this pin at VDDI or DGND																																										
10	WR(SPI_RS)	I	Write enable in MCU parallel interface. - Display data/command selection pin in 4-line serial interface. - Second Data lane in 2 data lane serial interface. -If not used, please fix this pin at VDDI or DGND.																																										
11	RD	I	Read enable in 8080 MCU parallel interface. -If not used, please fix this pin at VDDI or DGND.																																										
12	VSYNC	I	Vertical (Frame) synchronizing input signal for RGB interface operation. -If not used, please fix to the VDDI or DGND.																																										
13	HSYNC	I	-Horizontal (Line) synchronizing input signal for RGB interface operation. - If not used, please fix to VDDI or DGND.																																										
14	ENABLE	I	Data enable signal for RGB interface operation. -If not used, please fix this pin at VDDI or DGND.																																										
15	DOTCLK	I	Dot clock signal for RGB interface operation. -If not used, please fix this pin at VDDI or DGND.																																										
16	SDA	I	When IM3: High, SPI interface input pin. -The data is latched on the rising edge of the SCL signal. -If not used, please fix this pin at VDDI or DGND level.																																										

17	DB0	I	-DB[17:0] are used as MCU parallel interface data bus. 8-bit I/F: when IM3:0, DB[7:0] are used; when IM3:1, DB[17:10] are used. 9-bit I/F: when IM3:0, DB[8:0] are used; when IM3:1, DB[17:9] are used. 16-bit I/F: when IM3:0, DB[15:0] are used; when IM3:1, DB[17:10] and DB[8:1] are used. 18-bit I/F: DB[17:0] are used. -DB[17:0] are used as RGB interface data bus. 6-bit RGB I/F: DB[5:0] are used. 16-bit RGB I/F: DB[17:13], DB[11:1] are used. 18-bit RGB I/F: DB[17:0] are used. -If not used, please fix this pin at VDDI or DGND.
18	DB1	I	
19	DB2	I	
20	DB3	I	
21	DB4	I	
22	DB5	I	
23	DB6	I	
24	DB7	I	
25	DB8	I	
26	DB9	I	
27	DB10	I	
28	DB11	I	
29	DB12	I	
30	DB13	I	
31	DB14	I	
32	DB15	I	
33	DB16	I	
34	DB17	I	
35	SDO	O	SPI interface output pin. -The data is output on the falling edge of the SCL signal. -If not used, let this pin open.
36	LEDA	P	Anode of Backlight
37	LEDK	P	Cathode of Backlight
38	LEDK	P	Cathode of Backlight
39	LEDK	P	Cathode of Backlight
40	LEDK	P	Cathode of Backlight
41	XR(NC)		
42	YU(NC)		
43	XL(NC)		
44	YD(NC)		
45	GND	P	Ground

7-3 Timing Characteristics

7.4.1 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

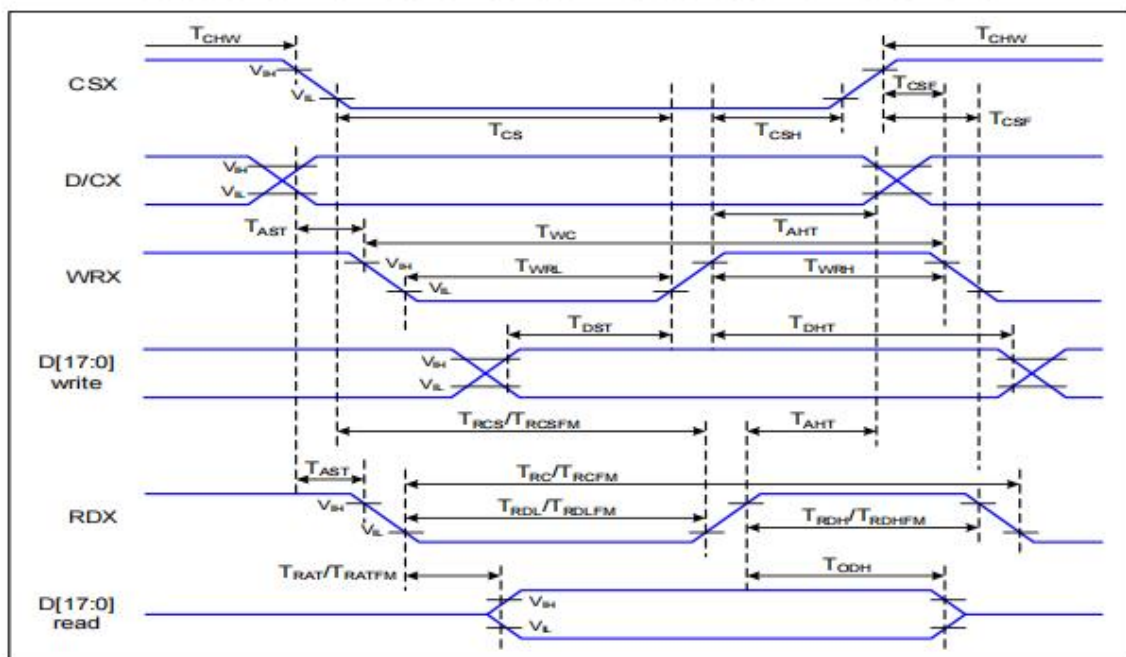


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25°C

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	-
	T _{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T _{CHW}	Chip select "H" pulse width	0		ns	-
	T _{CS}	Chip select setup time (Write)	15		ns	
	T _{RCS}	Chip select setup time (Read ID)	45		ns	
	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
WRX	T _{WC}	Write cycle	66		ns	-
	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T _{RC}	Read cycle (ID)	160		ns	When read ID data
	T _{RDH}	Control pulse "H" duration (ID)	90		ns	
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T _{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF

	T_{DHT}	Data hold time	10		ns
	T_{RAT}	Read access time (ID)		40	ns
	T_{RATFM}	Read access time (FM)		340	ns
	T_{ODH}	Output disable time	20	80	ns

Table 4 8080 Parallel Interface Characteristics



Figure 2 Rising and Falling Timing for I/O Signal

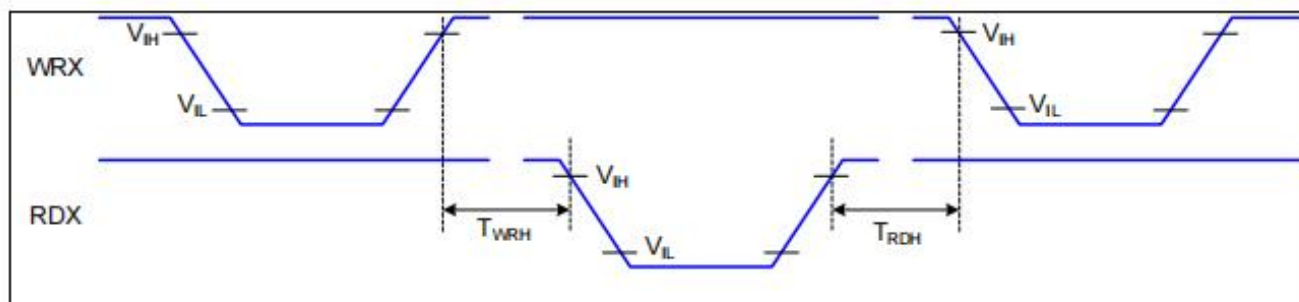


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (T_R , T_F) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

7.4.2 Serial Interface Characteristics (3-line serial):

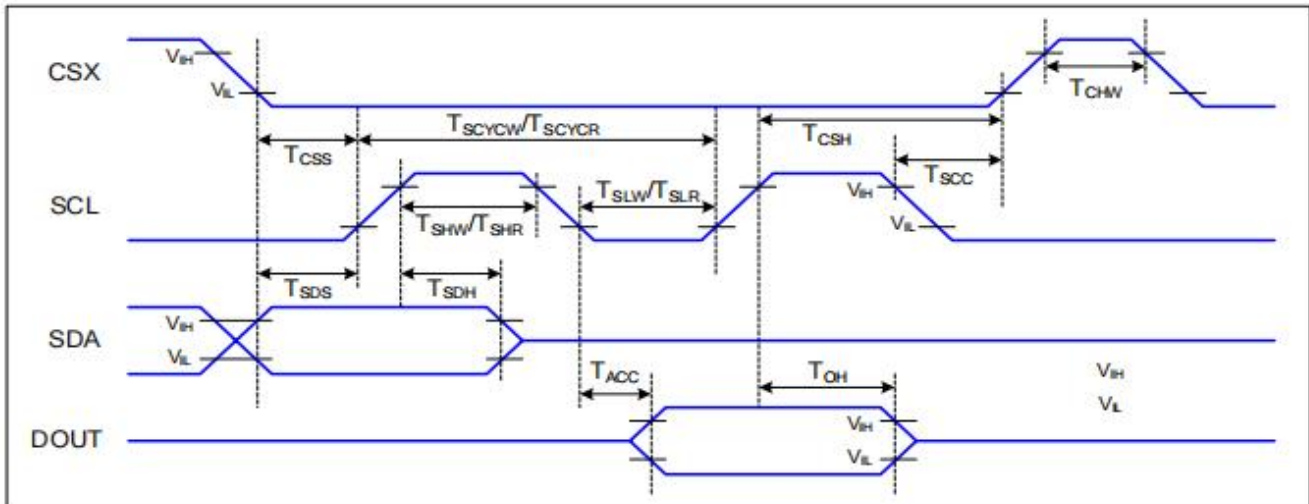


Figure 4 3-line serial Interface Timing Characteristics

$V_{DDI}=1.65$ to $3.3V$, $V_{DD}=2.4$ to $3.3V$, $AGND=DGND=0V$, $T_a=25^{\circ}C$

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	16		ns	
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 5 3-line serial Interface Characteristics

Note1 : The rising time and falling time (T_r , T_f) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of V_{DDI} for Input signals

Note2: In the read sequence of serial interface, the 500nsec delay time is needed between read command and first read clock..

7.4.3 Serial Interface Characteristics (4-line serial):

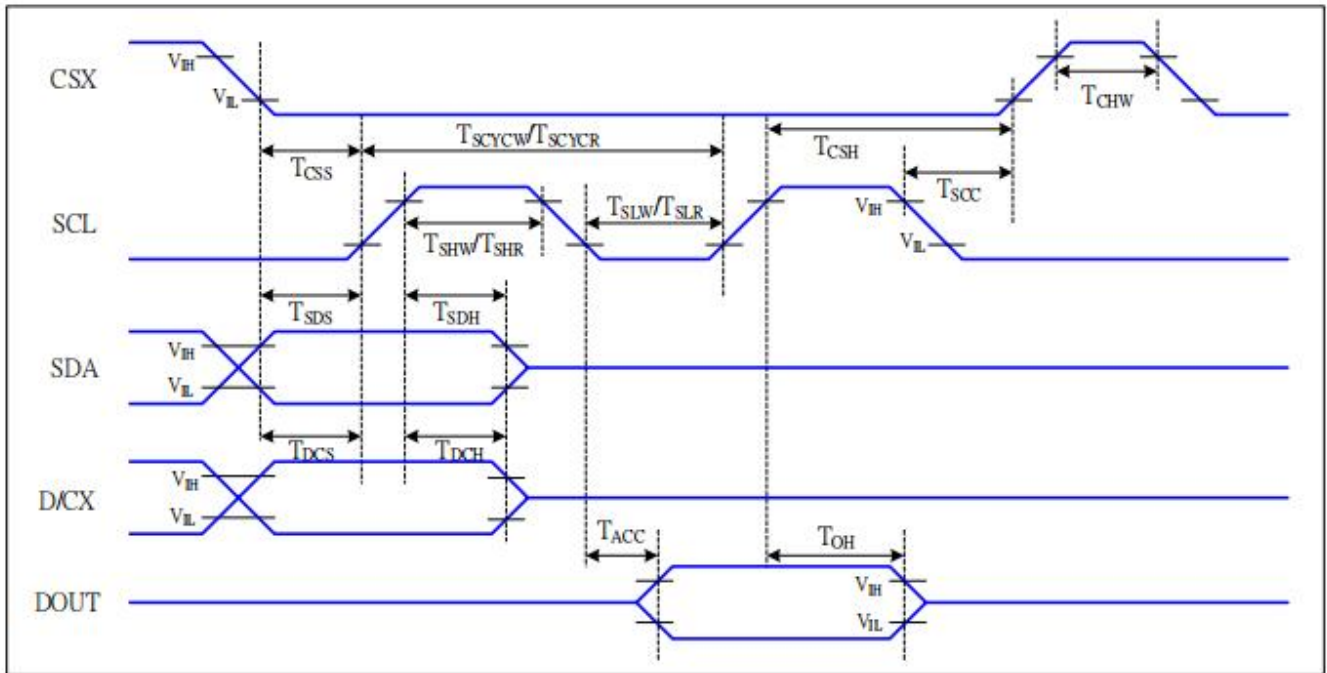


Figure 5 4-line serial Interface Timing Characteristics

$V_{DDI}=1.65$ to $3.3V$, $V_{DD}=2.4$ to $3.3V$, $AGND=DGND=0V$, $T_a=25^{\circ}C$

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCH}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYC}	Serial clock cycle (Write)	16		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYC}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 6 4-line serial Interface Characteristics

7.4.4 RGB Interface Characteristics:

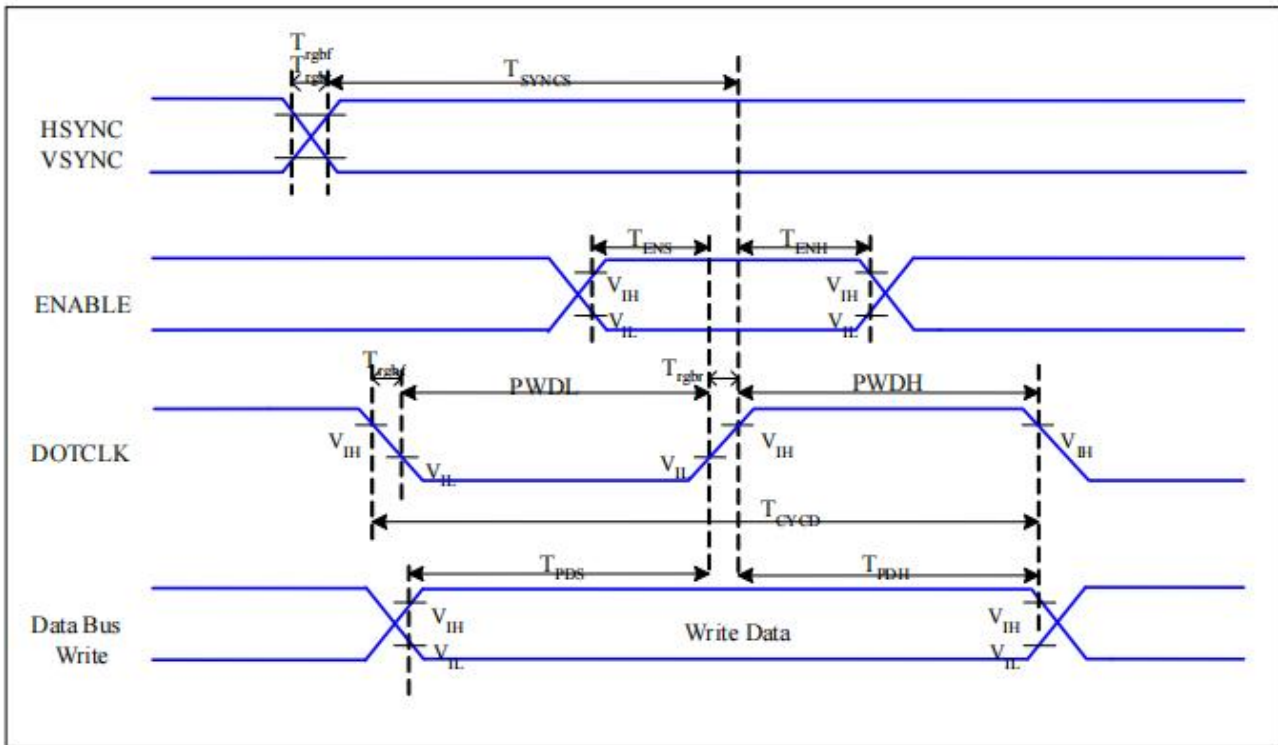


Figure 6 RGB Interface Timing Characteristics

VDDI= 1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25°C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	25	-	ns	
	T _{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T _{PDS}	PD Data Setup Time	50	-	ns	
	T _{PDH}	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	35	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	35	-	ns	

	T_{ENH}	Enable Hold Time	35	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	35	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	35	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	80	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	10	ns	
DB	T_{PDS}	PD Data Setup Time	35	-	ns	
	T_{PDH}	PD Data Hold Time	35	-	ns	

Table 8 6 Bits RGB Interface Timing Characteristics

7.4.5 Reset Timing:

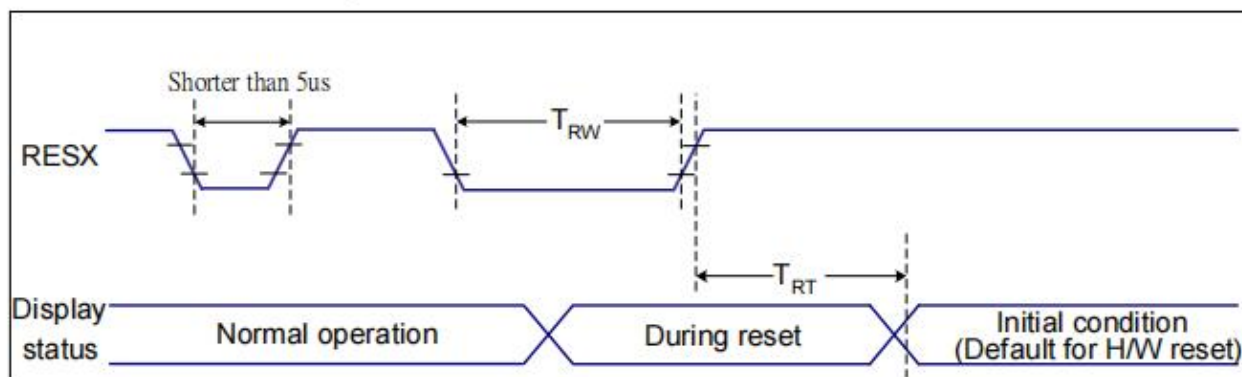


Figure 7 Reset Timing

$VDDI=1.65$ to $3.3V$, $VDD=2.4$ to $3.3V$, $AGND=DGND=0V$, $T_a=25^{\circ}C$

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Table 9 Reset Timing

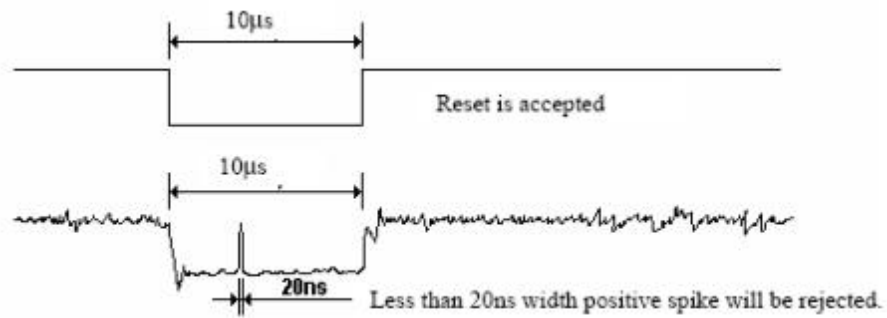
Notes:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (t_{RT}) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out-mode. The display remains the blank state in Sleep In-mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

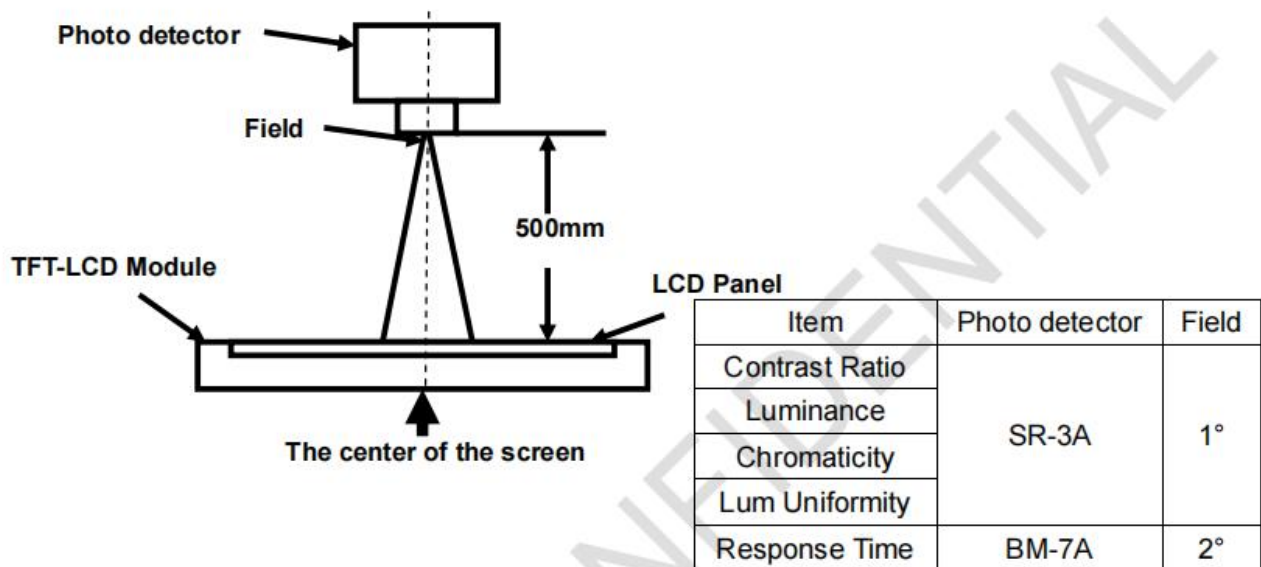
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

8. Electro-Optical Characteristics

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr +Tf	$\theta_x = \theta_y = 0$	---	20	30	ms	Note 1
Contrast Ratio		CR		250	350	---	---	Note 2
Transmittance		T%		5.5	6.0	---	%	
Color Chromaticity (CIE1931)	White	W x	$\theta_x = \theta_y = 0$	---	0.303	---	---	
		W y		---	0.359	---	---	
Viewing angle	θ_T		CR > 10	45	50	---	Deg.	Note 3
	θ_B			15	20	---		
	θ_L			40	45	---		
	θ_R			40	45	---		

Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80)。

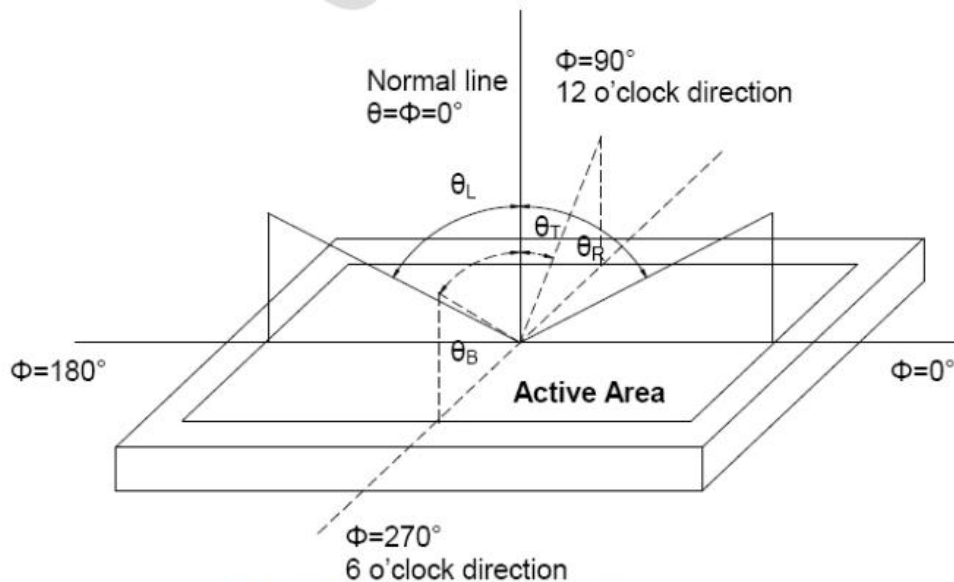


Fig. 1 Definition of viewing angle

Note 3: Definition of contrast ratio

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD is on the "White" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

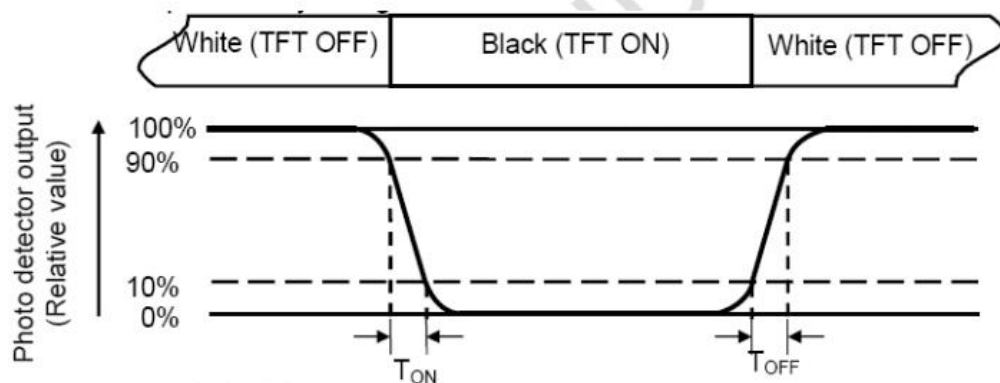
"White state": The state is that the LCD should driven by V_{white} .

"Black state": The state is that the LCD should driven by V_{black} .

V_{White} : To be determined V_{Black} : To be determined.

Note 4: Definition of response time

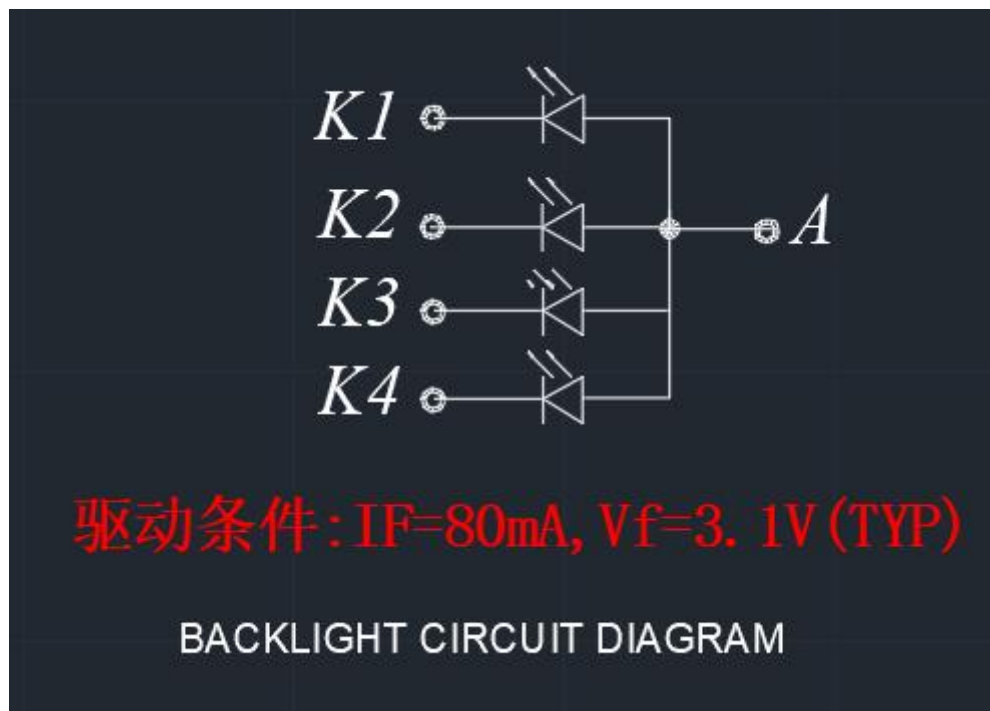
The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

Note(4) Backlight circuit



9. Inspection Standards

1. AQL(Acceptable Quality Level)

AQL of major and minor defect

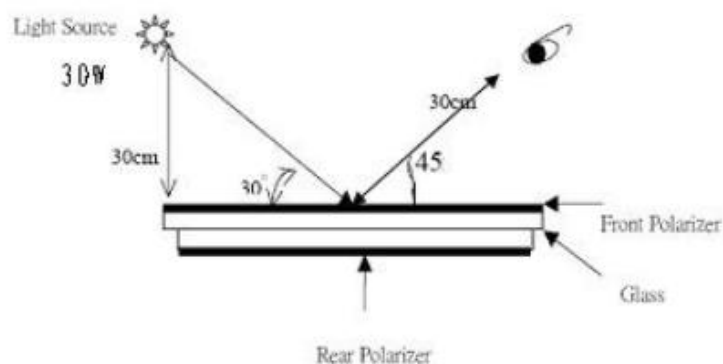
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINOR DEFECT
0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30, a distance of 30cm with normal eye, with an angle of 45 degree to check the products without uncovering the film!

(As shown below)

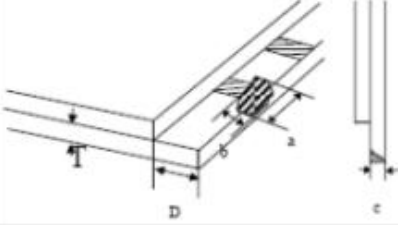
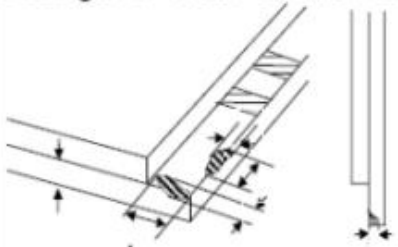


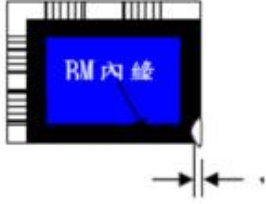
3. Inspection item and criteria

3.1 Visual inspection criterion in immobility

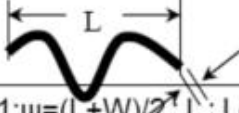
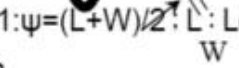
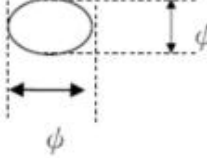
3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks (Major defect)	1.Linear cracks on panel 【 Reject】 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage 1) $b \leq 1/3$ Pin width(non bonding area) 【 Accept】 2) bonding area $\leq 0.5\text{mm}$ 【 Accept】	a:Length, b:Width
4	Pin-side , conductive area damaged (minor defect)	(a c : disregards) $b \leq 1/3$ of effective length for bonding electrode 【 Accept】	a:Length·b:Width·c:Thickness 
5	Pin-side , non-conductive area damaged (minor defect)	1) Damage area don't touch the ITO (Inclueing contraposition mark,except scribing mark) 【 Accept】 2) $c < T$ $b \leq BM$ 1/3 of width 【 Accept】 3) $c = T$ b not touch the seal glue 【 Accept】 4) a disregards	a:Length·b:Width·c:Thickness 

No	Defect item	Criteria	Remark
6	Non-pin-side damage (minor defect)	$c < T$	c : Thickness b : width of damage 
		1) b exceeds 1/3 BM	
		【Reject】	
		$c = T$ b not touch the seal glue 【Reject】	

3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber 、glass cratch 、polarizer scratch/folded (minor defect)	Specification	Allowable	note1: L : Length , W : Width note2: disregard if out of AA 
		$0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	
2	Polarizer bubble 、 concave and convex (minor defect)	$\psi \leq 0.2\text{mm}$	disregard	note 1: $\psi = (L+W)/2$; L : Length , W : Width note2: disregard if out of AA 
		$0.2\text{mm} < \psi \leq 0.3\text{mm}$	2	
		$0.3\text{mm} < \psi \leq 0.5\text{mm}$	1	
		$0.5\text{mm} < \psi$	0	
3	Black dots 、dirty dots 、 impurities 、eyewinker (Major defect)	$\psi \leq 0.15\text{mm}$	disregard	note2: disregard if out of AA 
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
4	Polarizer prick (Major defect)	$\psi \leq 0.1\text{mm}$	disregard	note1: $\psi = (L+W)/2$; L = Length , W = Width note2: the distance between two dots $> 5\text{mm}$
		$0.1\text{mm} < \psi \leq 0.25\text{mm}$	3	
		$\psi > 0.25\text{mm}$	0	

3.1.3 .FPC

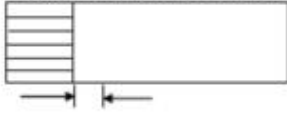
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【 Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【 Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		$\psi \leq 0.25\text{mm}$	2	
		$\psi > 0.25$	0	

3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift (minor defect)	1.shift spec: 1)glue to the polarize 【 Reject】 2) IC bare 【 Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【 Reject】 2)IC bare 【 Reject】	
2	No black tape (Major defect)	No black tape 【 Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【 Reject】	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film. 【 Reject】	

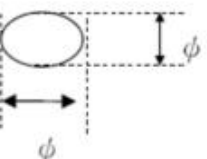
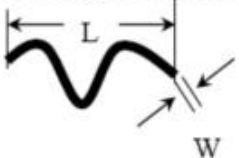
3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【 Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area 【Reject】 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) 【accept】	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer 【Reject】	Except of the special requirement .

3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display 【Reject】	
2	Missing line (Major defect)	Missing line 【Reject】	
3	Seg-com light and dark (Major defect)	Seg-com light and dark 【Reject】	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility 【Reject】	
5	Flicker of Pattern (Major defect)	Flicker of Pattern 【Reject】	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current 【Reject】	
8	Voltage out of specification (Major defect)	Voltage out of specification 【Reject】	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code 【Reject】	
10	Dark light, Flicker (Major defect)	Dark light, Flicker 【Reject】	

No	Defect item	Criteria	Remark	
11	Black/White dots · Dirty dots · eyewinker (Major defect)	Specification	Allowable	Note1: disregard if out of AA 
		$\psi \leq 0.15\text{mm}$	disregard	
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
12	Fiber · glass cratch · polarizer scratch/folded (minor defect)	$W \leq 0.03\text{mm}$	disregard	note1: L : Length · W : Width note2: disregard if out of AA 
		$0.03\text{mm} < W \leq 0.05\text{mm} ;$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm} ;$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm} ; L > 3.0\text{mm}$	0	

10.Records Of Version

Version	Revise Date	Page	Content
00	2025-12-15	ALL	New released